

	1	2	3	4	5	6	7
Layers	Bottom Layer						

Impedance Requirements

Layer	Impedance RG Spec	Impedance RP Spec (Ohm)	Impedance RP Spec (Ohm)
Trace Width (mm)	Trace Width (mm)	Trace Width (mm)	Trace Width (mm)
Bottom Layer			

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay	Solder Resist	0.012mm	3.8	
2	Top Solder	Copper	0.035mm	4.2	
3	Top Layer	FPC 0.2mm 35/35 copper	0.200mm	4.2	
4	Dielectric	Copper	0.035mm	4.2	
5	Mid-Layer 1	PFA 0.2mm	0.200mm	4.2	
6	Dielectric	Copper	0.035mm	4.2	
7	Mid-Layer 2	PFA 0.2mm	0.200mm	4.2	
8	Dielectric	Copper	0.035mm	4.2	
9	Signal Layer 1	PFA 0.2mm 35/35 copper	0.200mm	4.2	
10	Dielectric	Copper	0.035mm	4.2	
11	Signal Layer 2	PFA 0.2mm 35/35	0.200mm	4.2	
12	Dielectric	Copper	0.035mm	4.2	
13	Bottom Layer	Copper	0.035mm	4.2	
14	Bottom Solder	Solder Resist	0.012mm	3.8	

Supplementary Notes:

This board is formed creating a 4 layer board and then bonding bottom core and the fabricated 4 layer boards.

This process will create a 8 layer structure with 8 Cu layers and two drill hole.

Once the 4 layer board is drilled , plating to 0.5 Oz Cu is required. The bottom core and Cu are then bonded and drilled. Plated through holes should be plated to 0.5 Oz Cu (for the drill hole pairs between top and bottom layers).

Blisters and chemical fuming should be completed as final processing steps.

NOTES (UNLESS OTHERWISE SPECIFIED)

- BOND SPEED** - BOND SHALL BE MANUFACTURED TO MEET ALL SPECS LISTED UNDER IPC-460 LATEST REVISION
- WIRE PITCHES** - PER DRG TOL HOLE DIA DRG TOL
- IS FOR LAPMENTS AND MINIMUM SHALL BE MAXIMUM VALUE OF 10% C
- COPPER FIB WEHT** - SEE TABLE FOR FINCH-UP DETAIL
- PLATING** - 0.5oz 0.75oz 1oz 2oz 3oz
- ZINC** - 0.001 oz/inch 0.002 oz/inch 0.003 oz/inch 0.004 oz/inch 0.005 oz/inch
- GOLD PLATE** - ONLY GOLDEN PRIME HAS BEEN SPECIFIED IPC-460-HQS OR FOR GREEN WHITE BLACK OTHER
- ELAPROCES** - LIT - ONLY EXIST BAKED INE
- TOP-BOTTOM TOP ONLY BOTTOM ONLY NONE
- METE BLANK OTHER
- IMPEDANCE CONTROL** - NO YES SEE TABLE FOR DETAIL
- ELECTRONIC TEST** - DONE IPC-D-350A
- HLL PLATED AND NON-PLATED THROUGH HOLES ARE TO BE INCLUDED AT PREPARE**
- HLL HOLES LONGEST TOLERANCES ARE TO BE +/- .002 IN IN
- BORER FILES** - SUPPLIED BORER FILES MUST NOT BE PROVIDED WITHOUT PER
- LINO** - ONLY LINDS SUPPLIED IN BORER FILES WILL BE ACCEPTED
- TOLLING HOLES** - NO HOLES SHALL BE PERMITTED BETWEEN THE BOARD AREA, CO IN THE DRILL LINDS
- ADDITIONAL INFORMATION** - ADDITIONAL INFORMATION TO BE GIVEN +/- .002 LOCATIONS TO EXPANSION MARK

Notes: Board will go through (C) two 0.5 Oz plating processes.
Top & Bottom Layers finished copper weight 35oz ±platingmedium

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